



US00D875685S

(12) **United States Design Patent**
Barany et al.

(10) **Patent No.:** **US D875,685 S**

(45) **Date of Patent:** **** Feb. 18, 2020**

(54) **STACKABLE RF MODULES**

(71) Applicant: **PPC BROADBAND, INC.**, East
Syracuse, NY (US)

(72) Inventors: **David Barany**, Syracuse, NY (US);
Cameron James Adams, Camillus, NY
(US)

(73) Assignee: **PPC BROADBAND, INC.**, East
Syracuse, NY (US)

(**) Term: **15 Years**

(21) Appl. No.: **29/628,202**

(22) Filed: **Dec. 1, 2017**

(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/151**; D14/188; D14/496

(58) **Field of Classification Search**
USPC D14/162, 167-169, 175, 179, 188,
D14/194-198, 217, 257, 265, 299, 496,
D14/240, 242, 230; D13/151, 147;
D21/484, 486, 500-502

CPC B60R 11/0217; G06F 1/1688; G10K 9/22;
G10K 11/004; H03F 1/327; H04M 1/03;
H04M 1/035; H04N 5/642; H04N
21/4852; H04R 1/02; H04R 1/06; H04R
1/021; H04R 1/025; H04R 1/026; H04R
1/028; H04R 1/105; H04R 1/323; H04R
1/403; H04R 1/2834; H04R 5/02; H04R
7/20; H04R 9/06; H04R 9/025; H04R
2201/021; H04R 2400/00; H04R 2400/07;
H04R 2499/11; H04R 2499/13; H04R
2499/15; H04S 3/00; H04S 7/30

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D301,239 S * 5/1989 Chino D13/146
D301,240 S * 5/1989 Chino D13/146

D399,846 S *	10/1998	Beggs	D14/217
D404,713 S *	1/1999	Hsiang	D13/147
D408,364 S *	4/1999	Hsiang	D13/151
D452,682 S *	1/2002	Inoue	D13/151
D475,020 S *	5/2003	Soulodre	D13/151
D577,038 S *	9/2008	Nakamura	D14/385
D607,413 S *	1/2010	Egan	D13/151
D607,414 S *	1/2010	Egan	D13/151
D673,914 S *	1/2013	Witkowski	D13/151
D673,916 S *	1/2013	Regnier	D13/151
D751,509 S *	3/2016	Hanson	D13/151
D756,935 S *	5/2016	Hanson	D13/151
9,813,458 B2 *	11/2017	Bailey	H04L 12/2801
D823,258 S *	7/2018	Hanson	D13/151
D840,943 S *	2/2019	Hanson	D13/151
D859,321 S *	9/2019	Li	D13/151
2009/0077608 A1 *	3/2009	Romerein	H03H 7/463 725/127

(Continued)

Primary Examiner — Keli L Hill

(74) *Attorney, Agent, or Firm* — Oliff PLC

(57) **CLAIM**

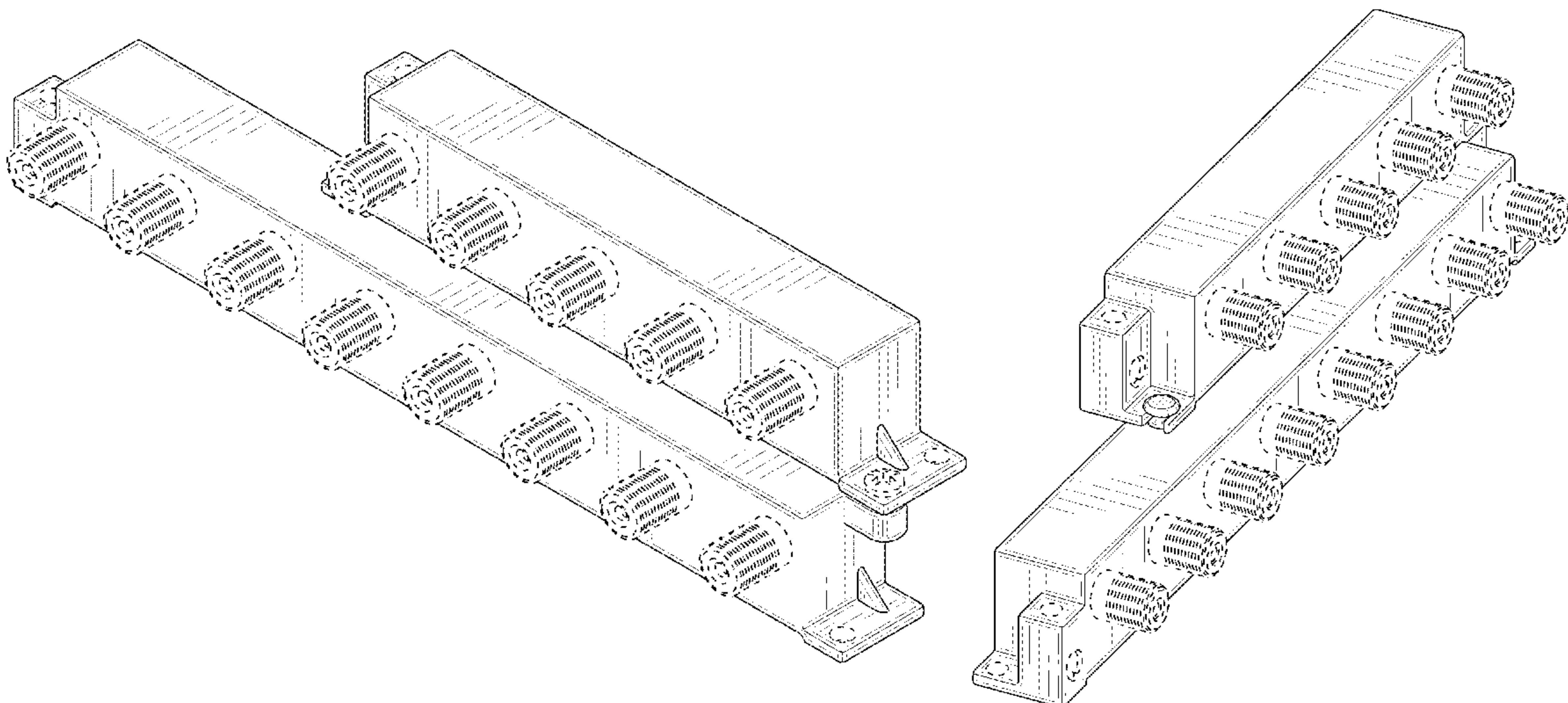
The ornamental design for stackable RF modules, as shown and described.

DESCRIPTION

FIG. 1 is a front, top, left-side view of the stackable RF modules;
FIG. 2 is a front, top, right-side view thereof;
FIG. 3 is a front elevational view thereof;
FIG. 4 is a rear elevational view thereof;
FIG. 5 is a right-side elevational view thereof;
FIG. 6 is a left-side elevational view thereof;
FIG. 7 is a top plan view thereof; and,
FIG. 8 is a bottom plan view thereof.

The broken lines depict unclaimed portions of the stackable RF modules, and thus form no part of the claimed design.

1 Claim, 8 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

2013/0133019 A1* 5/2013 Montena H04N 21/61
725/127
2019/0221975 A1* 7/2019 Barany H01R 25/006

* cited by examiner

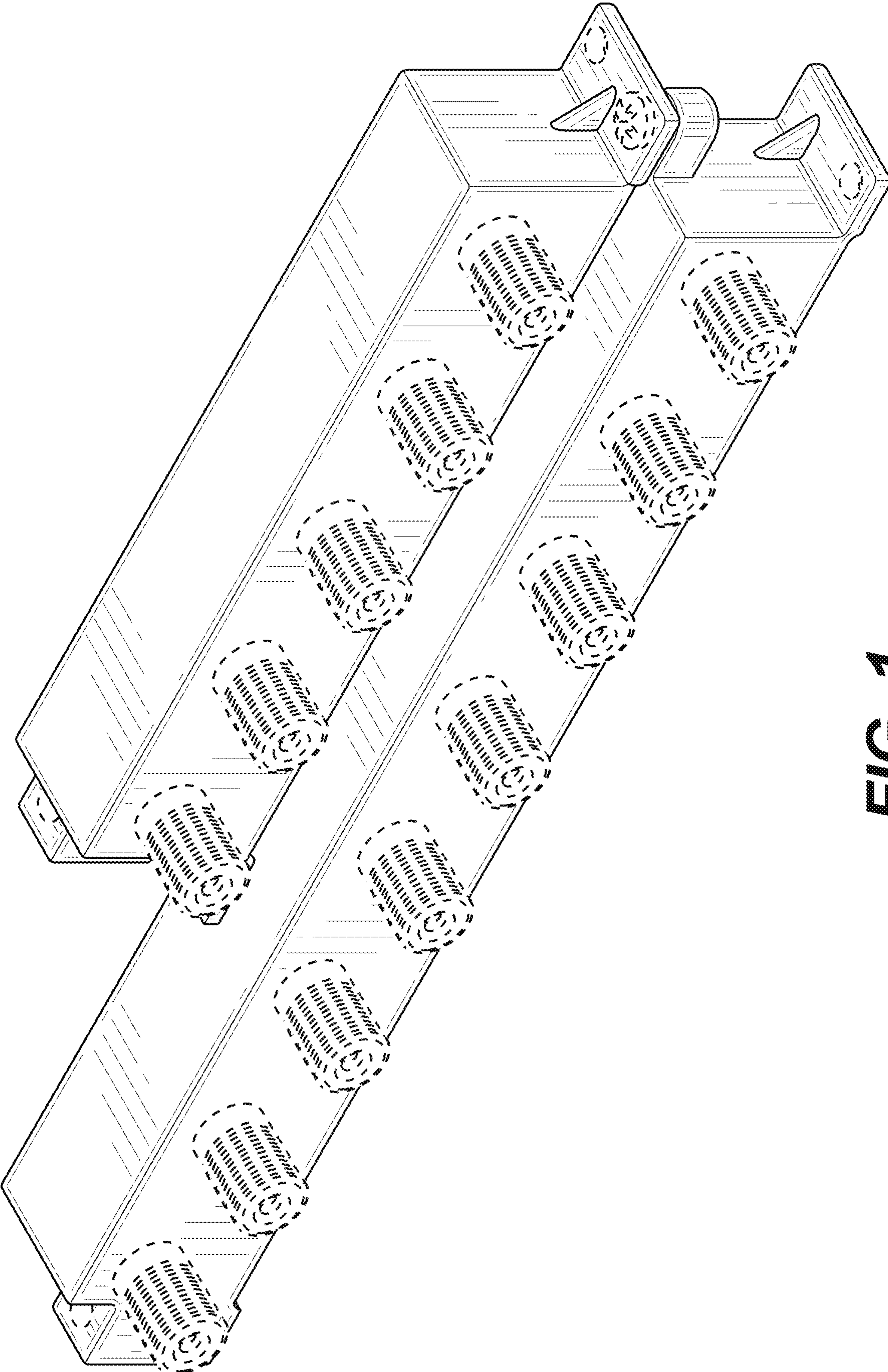


FIG. 1

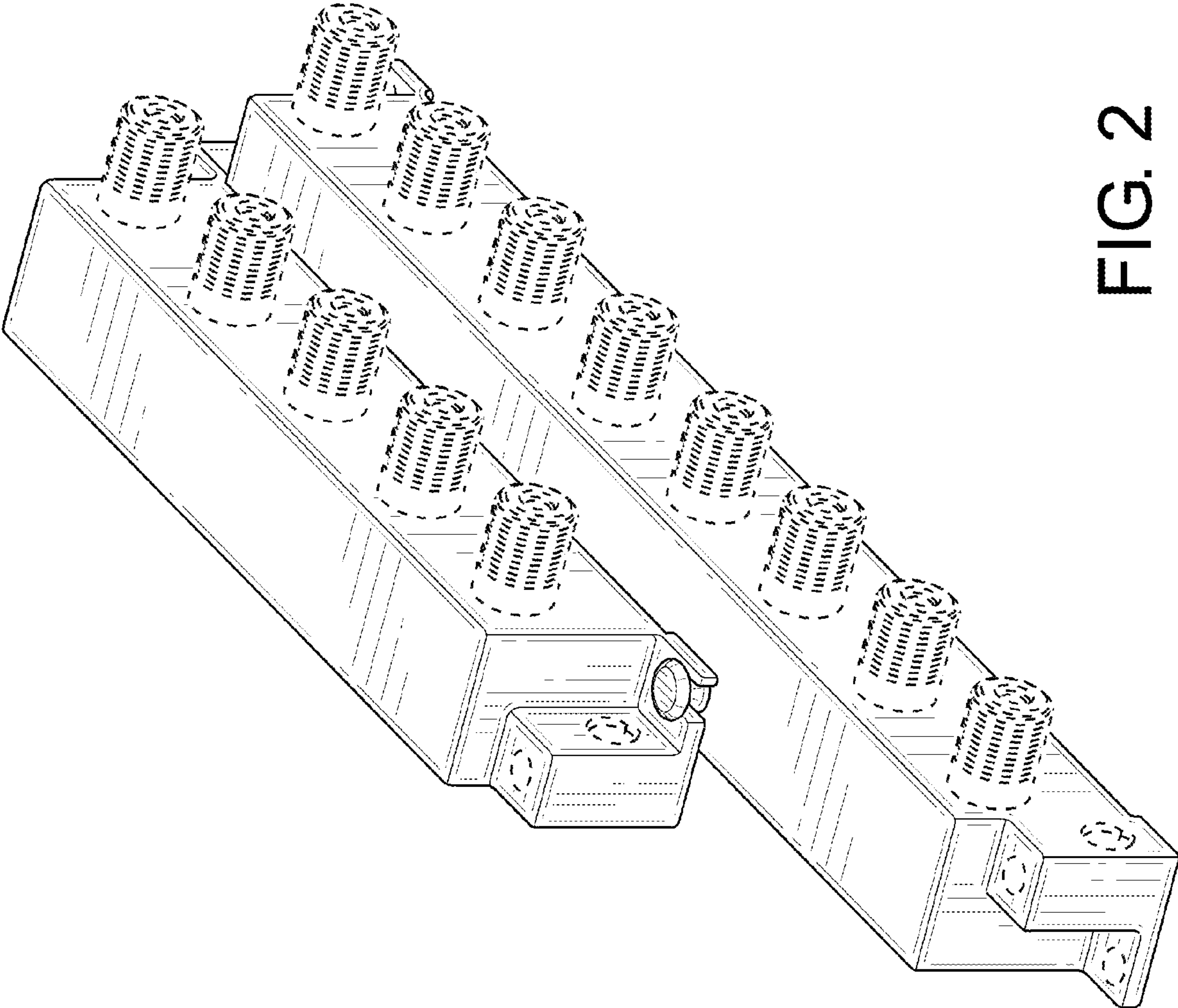


FIG. 2

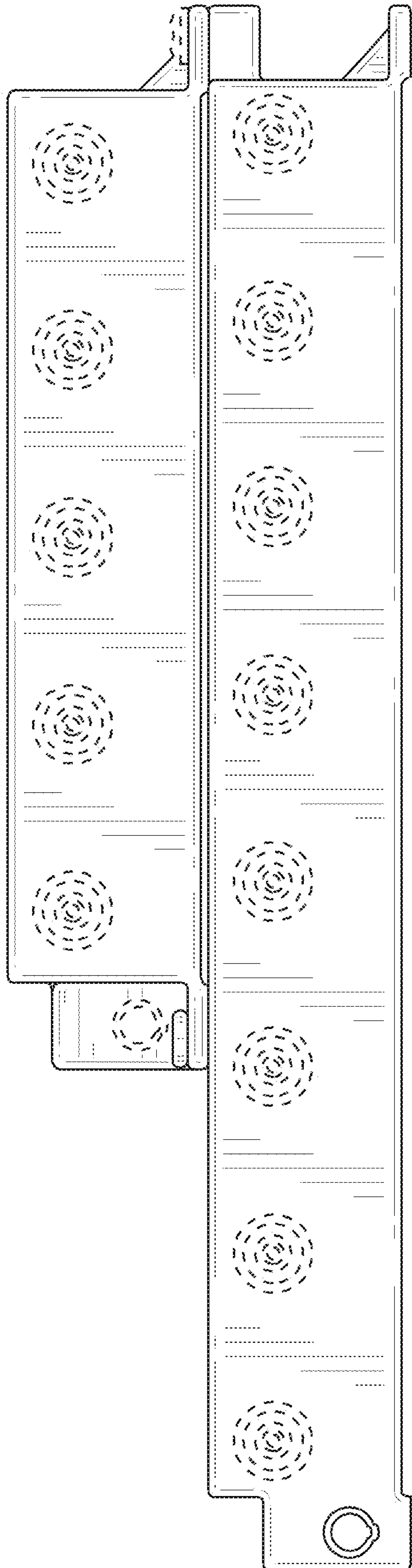


FIG. 3

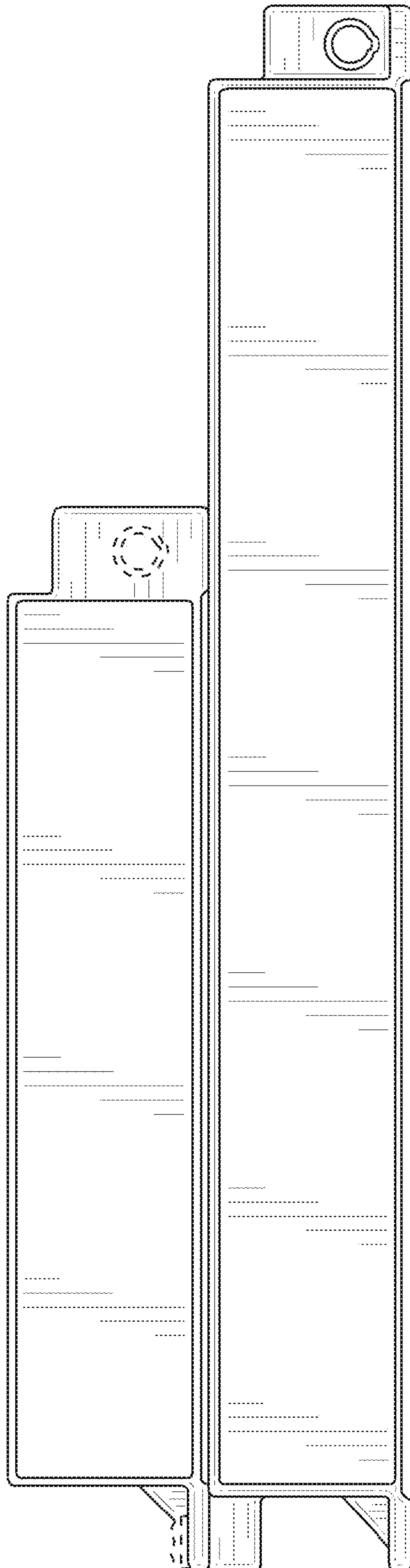


FIG. 4

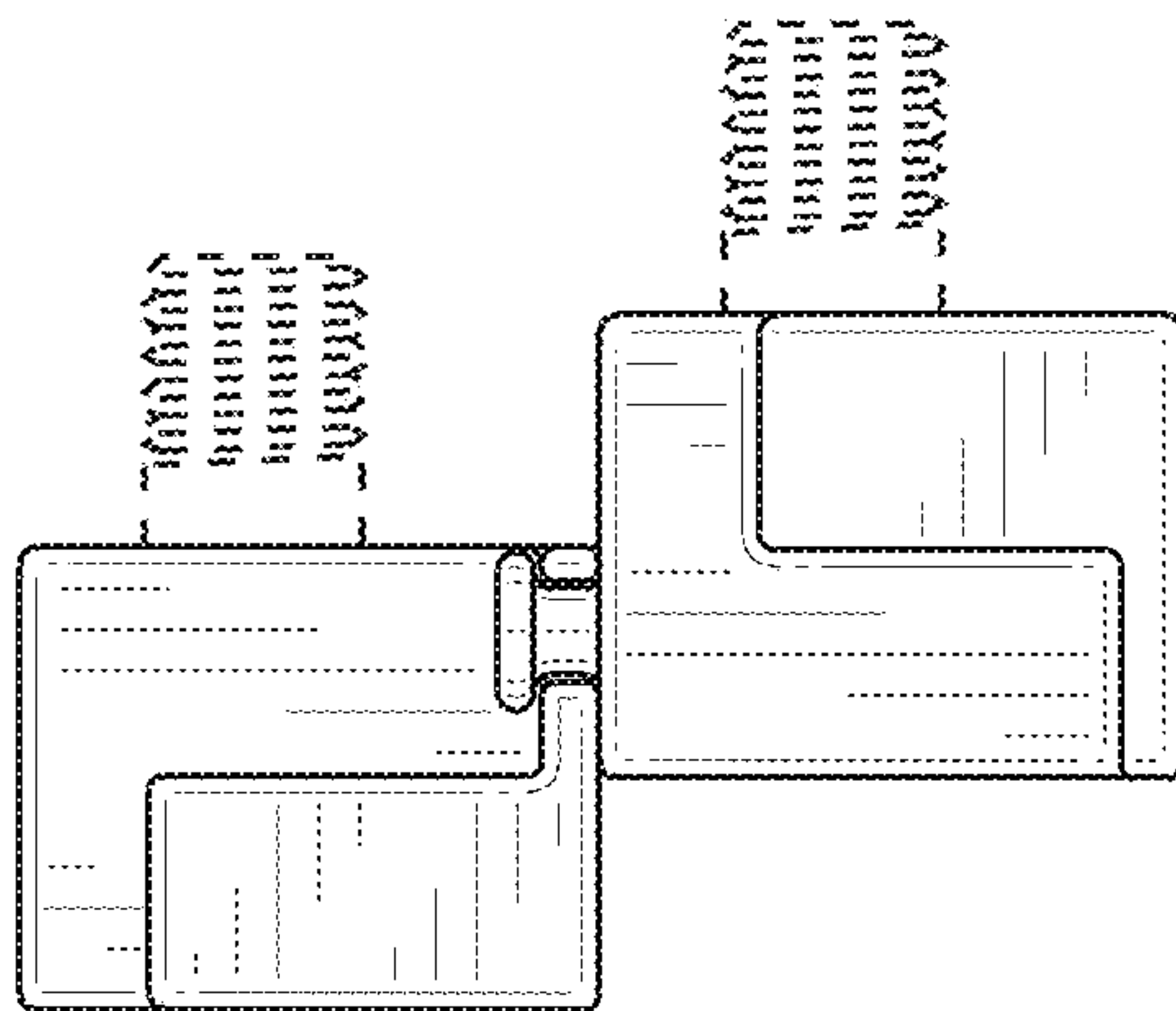


FIG. 5

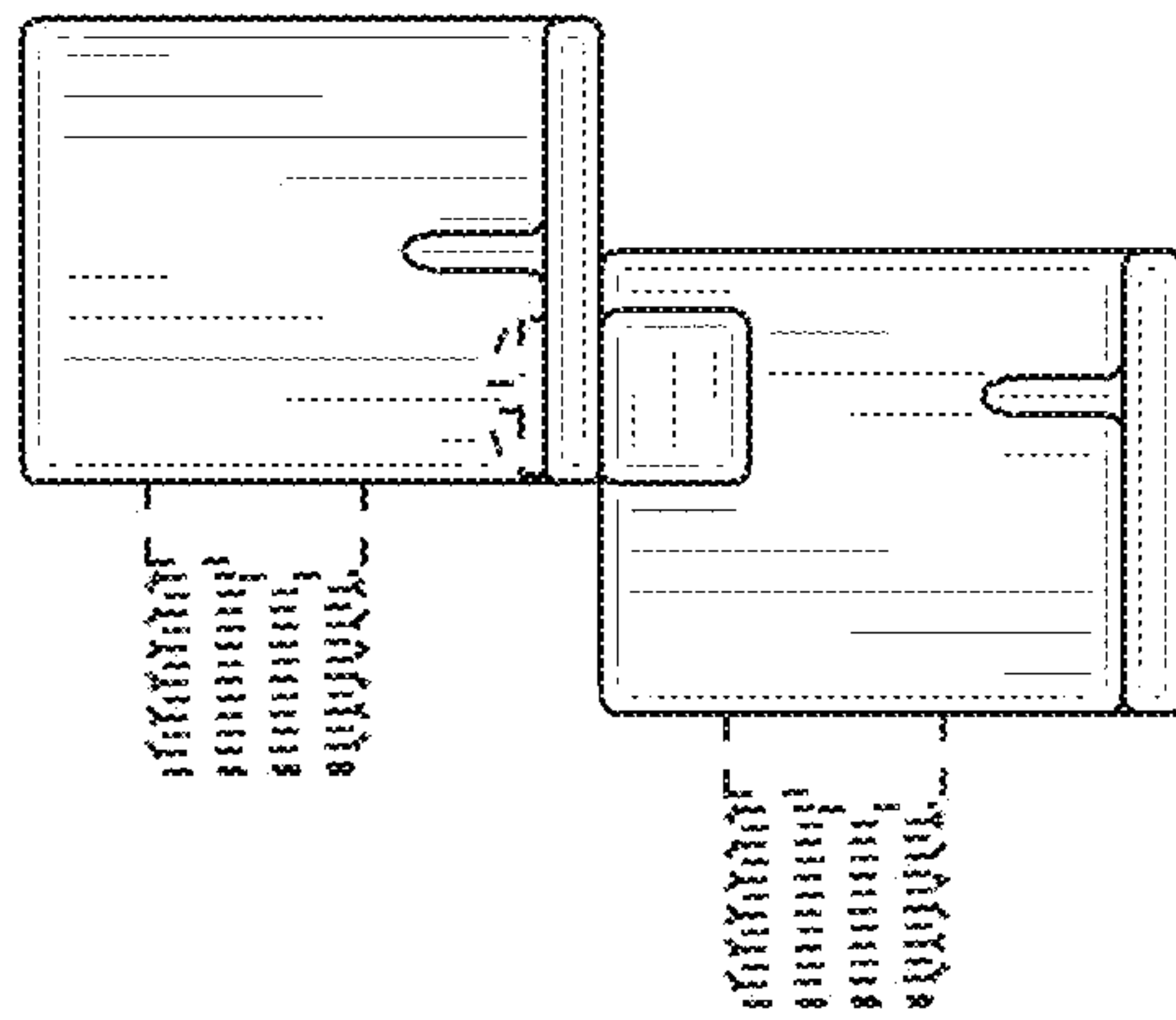


FIG. 6

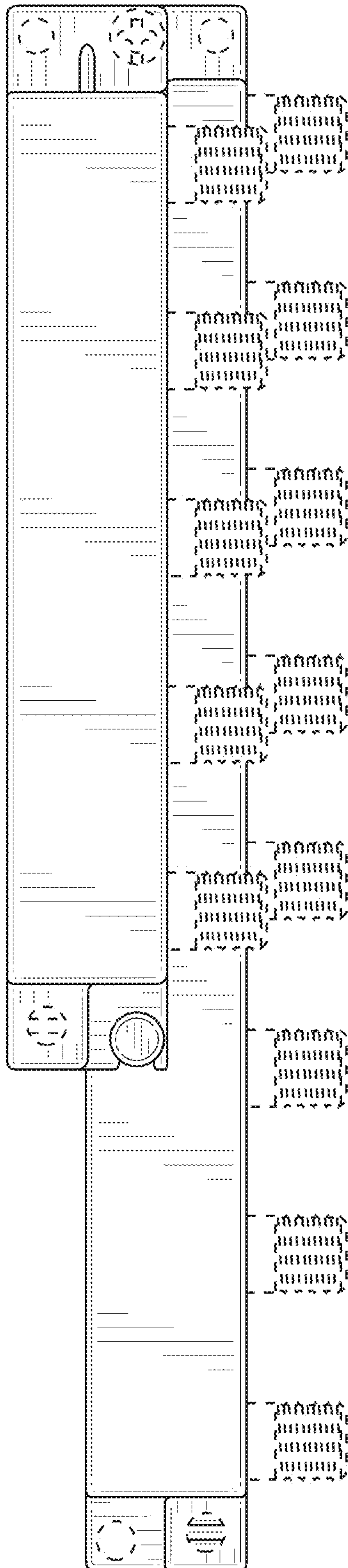


FIG. 7

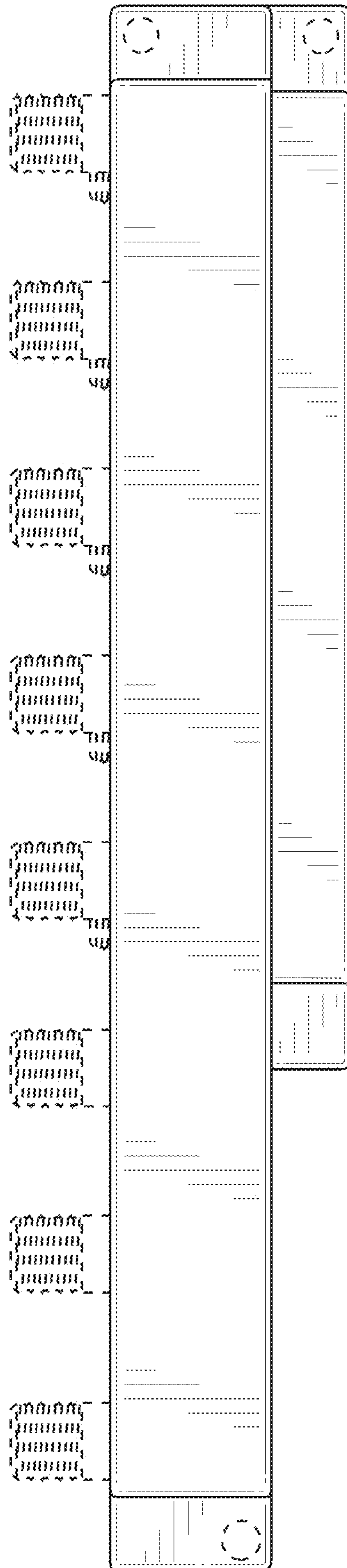


FIG. 8